

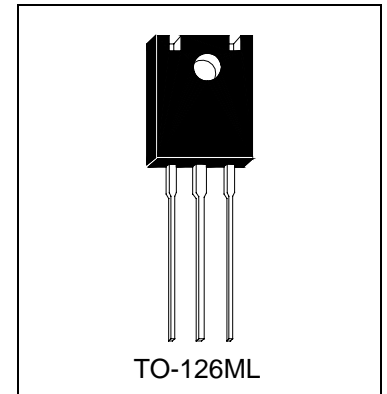


HSB772

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HSB772 is designed for using in output stage of 1w audio amplifier, voltage regulator, DC-DC converter and relay driver.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 1.4 W
 Total Power Dissipation (Tc=25°C) 10 W
- Maximum Voltages and Currents
 BVCBO Collector to Base Voltage -40 V
 BVCEO Collector to Emitter Voltage -30 V
 BVEBO Emitter to Base Voltage -5 V
 IC Collector Current (DC) -3 A
 IC Collector Current (Pulse) -7 A
 IB Base Current (DC) -0.6 A

Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA
BVCEO	-30	-	-	V	IC=-1mA
BVEBO	-5	-	-	V	IE=-10uA
ICBO	-	-	-1	uA	VCB=-30V
IEBO	-	-	-1	uA	VEB=-3V
*VCE(sat)	-	-0.3	-0.5	V	IC=-2A, IB=-0.2A
*VBE(sat)	-	-1	-2	V	IC=-2A, IB=-0.2A
*hFE1	30	-	-		IC=-20mA, VCE=-2V
*hFE2	100	200	400		IC=-1A, VCE=-2V
fT	-	80	-	MHz	IC=-0.1A, VCE=-5V
Cob	-	55	-	pF	VCB=-10V, f=1MHz, IE=0

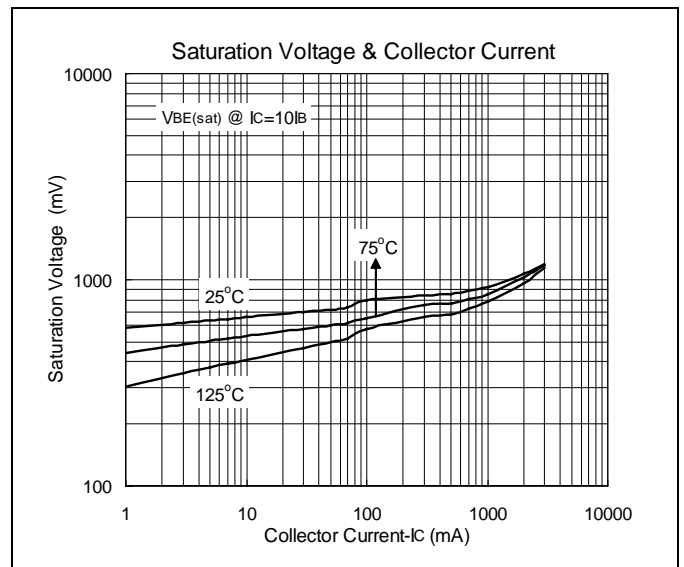
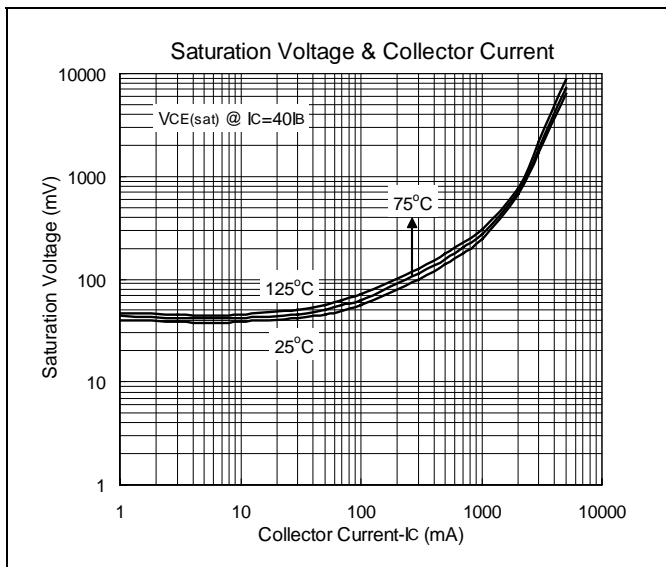
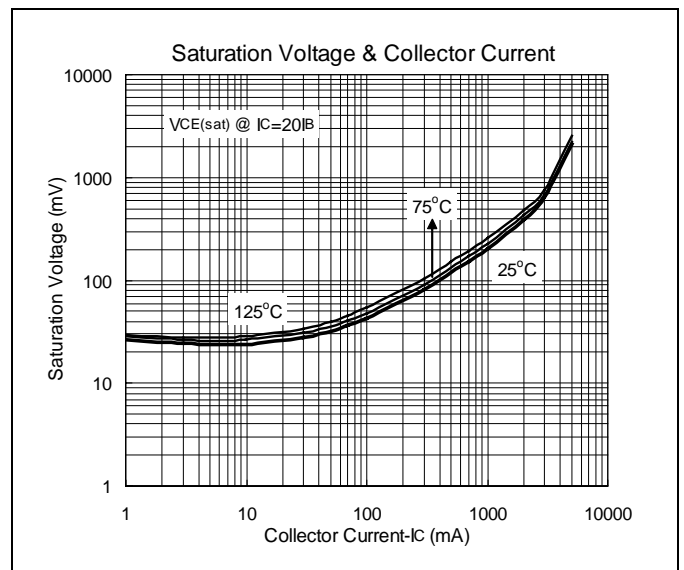
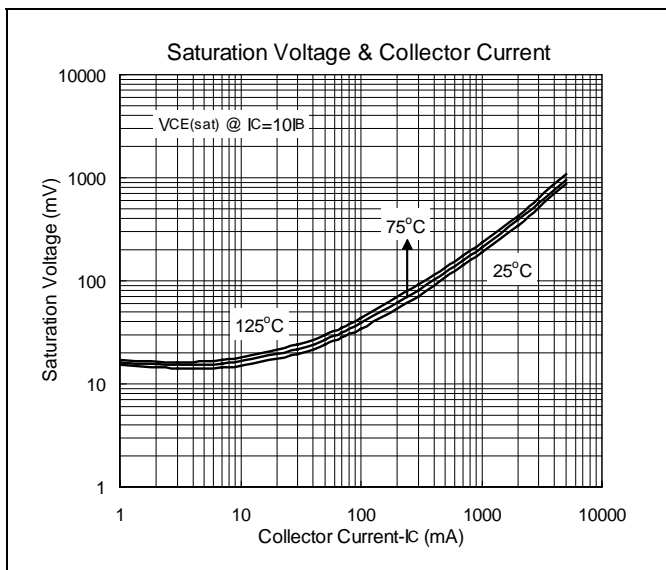
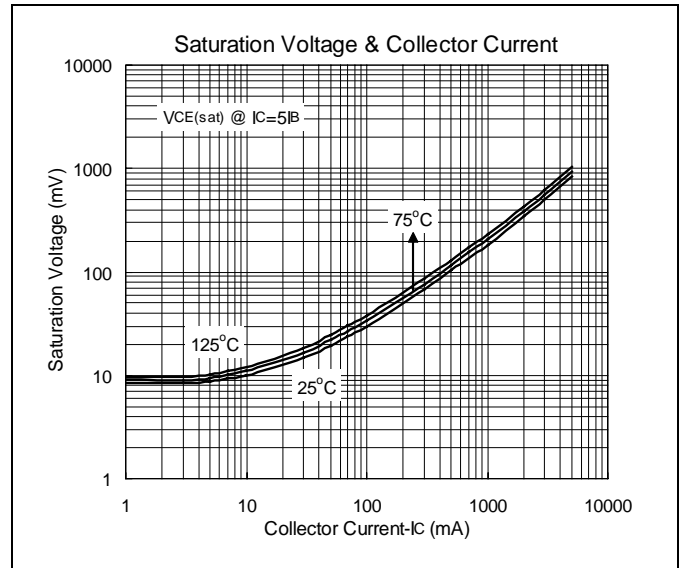
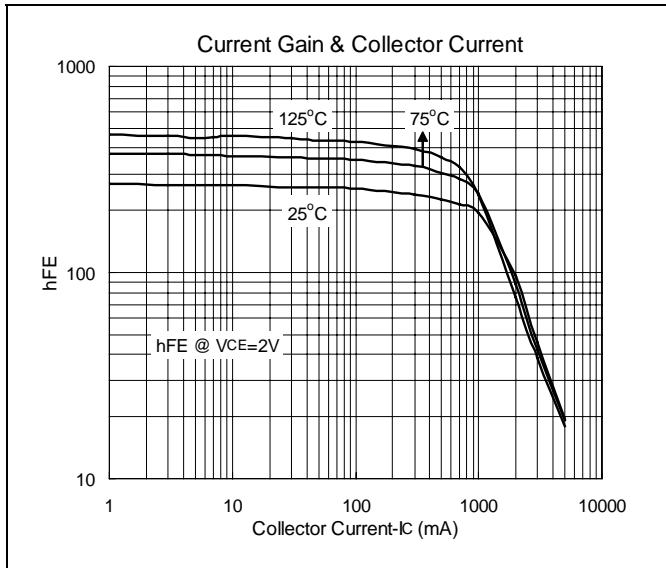
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

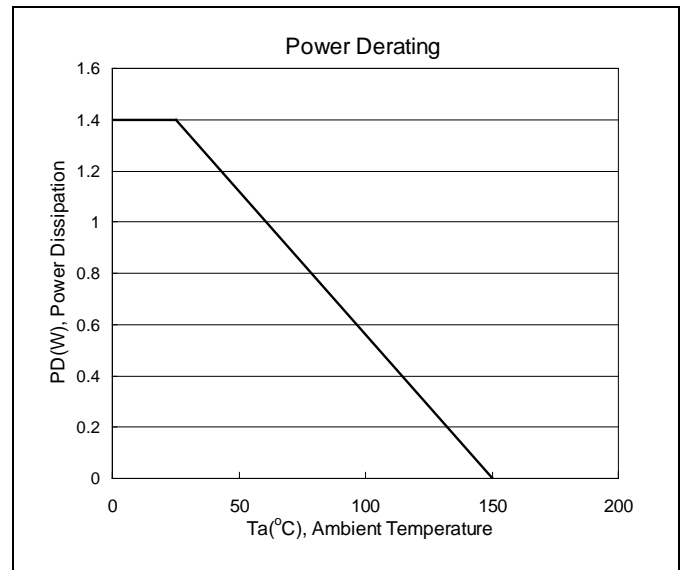
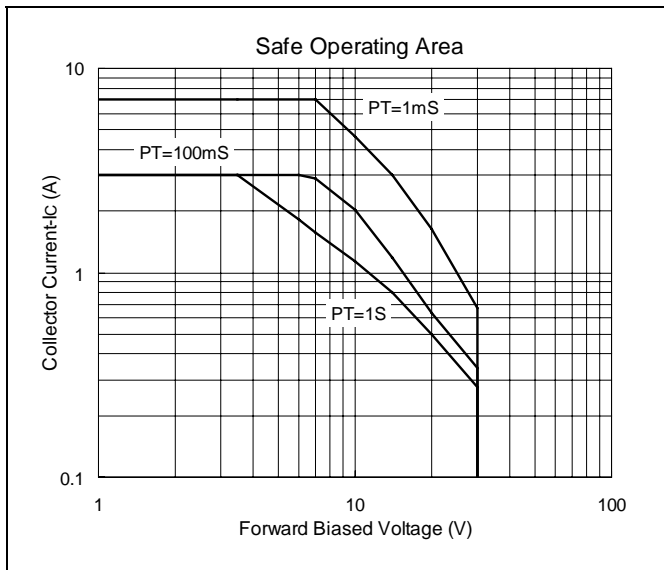
Classification Of hFE2

Rank	Q	P	E
Range	100-200	160-320	200-400



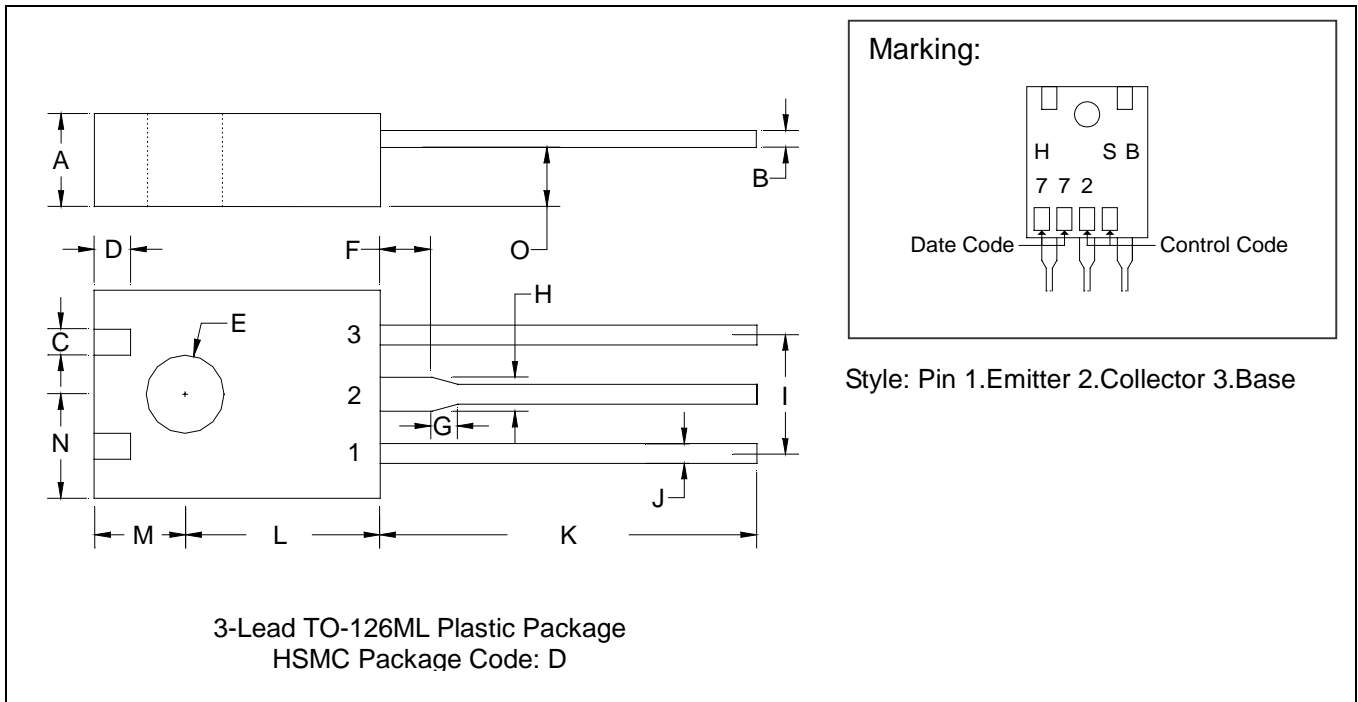
Characteristics Curve







TO-126ML Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes: 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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